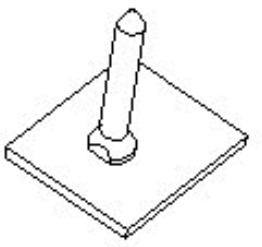
This document was generated on 05/19/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 0740760001
Status: Active
Overview: vhdm__hsd
Description: VHDM-HSD™ Free-Standing Guide Pin



Series image - Reference only

Documents:
Drawing (PDF)
RoHS Certificate of Compliance (PDF)

General

Product Family	Backplane Connectors
Series	74076
Application	Backplane
Application Tooling Documents	Tooling Manual
Comments	Dimension C = 6/8 row
Component Type	Guide
Overview	vhdm__hsd
Product Name	VHDM®, VHDM-HSD™
Style	N/A

Physical

Circuits (Loaded)	0
Circuits (maximum)	0
Durability (mating cycles max)	200
Keying to Mating Part	None
Number of Columns	N/A
Number of Pairs	Open Pin Field
Number of Rows	0
Orientation	N/A
PCB Retention	None
PCB Thickness Recommended (in)	0.070 In, 0.157 In
PCB Thickness Recommended (mm)	1.80 mm, 4.00 mm
Packaging Type	Bag
Pitch - Mating Interface (in)	0.000 In
Pitch - Mating Interface (mm)	0.00 mm
Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	N/A

Electrical

Current - Maximum per Contact	N/A
Data Rate	N/A
Shielded	No
Voltage - Maximum	N/A

Material Info

Reference - Drawing Numbers

Sales Drawing	SD-74076-002, SD-74076-005

VHDM, VHDM-HSD and Very High Density Metric are trademarks of Amphenol Corporation

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Not Reviewed
Halogen-Free Status
Halogen-Free

China RoHS

Need more information on product environmental compliance?

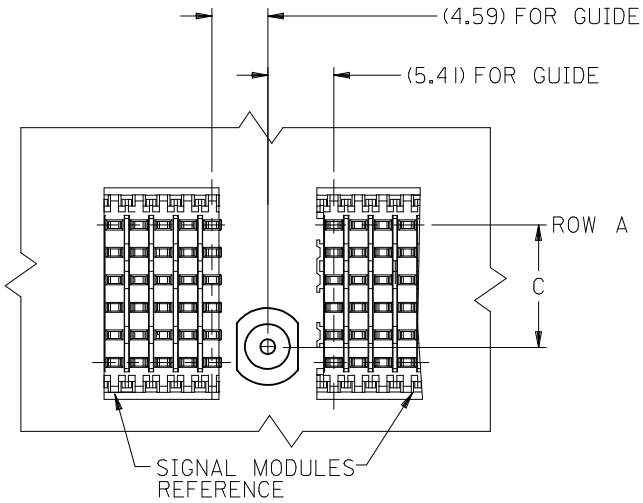
Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

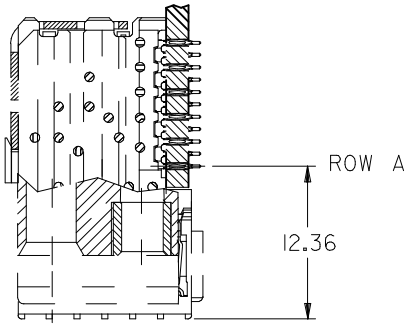
Please visit the Contact Us section for any non-product compliance questions.

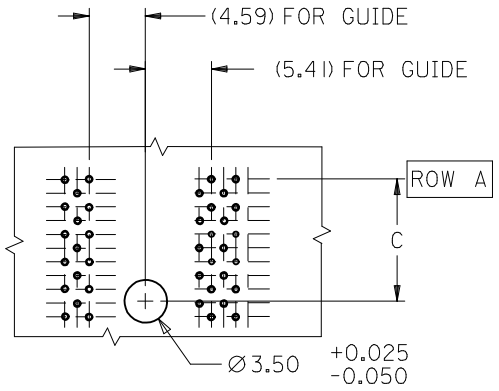
Search Parts in this Series
74076Series

This document was generated on 05/19/2010

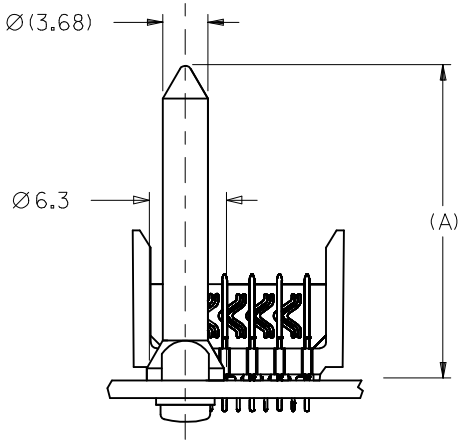
PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

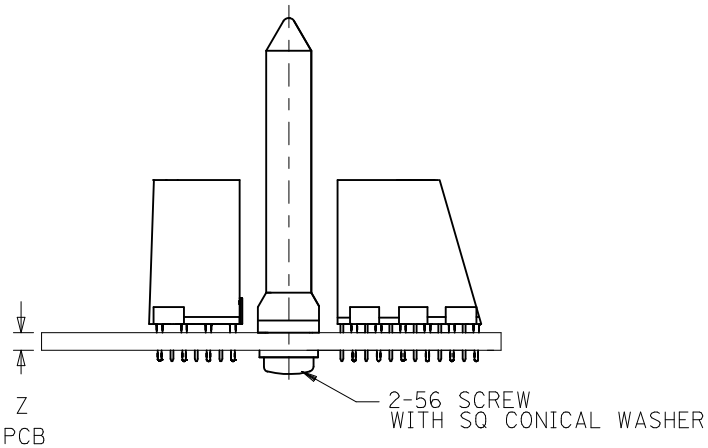






BACKPLANE HOLE PATTERN
FREE STAND GUIDE PIN





KIT NUMBER	DIM Z BOARD THICKNESS	DIM A
74076-0001	1.8-4.0	25.8
74076-0002	>4.0-9.00	25.8
74076-0005	1.8-4.0	19.9
74076-0006	>4.0-9.00	19.9

NOTES:

PACKAGING: STANDARD BULK PACK, 500 PER BAG
PACKAGE SCREWS AND GUIDE SEPARATE.

MATE WITH		DIM C
VHDM 6 ROW	GUIDE MODULE	9.96
	GROUND MODULE	9.26
	JOINER MODULE	9.26
VHDM 8 ROW	GUIDE MODULE	11.75
	GROUND MODULE	11.75
	JOINER MODULE	11.75

ADD PARTS
EC NO: UCP2009-0672
DRWN: JBINGHAM 2008/09/18
CH'KD: 2008/09/19
APPR: JLAURX 2008/09/19
DESCRIPTION
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.10	± ---
1 PLACE	± 0.15	± ---
ANGULAR ± 3 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

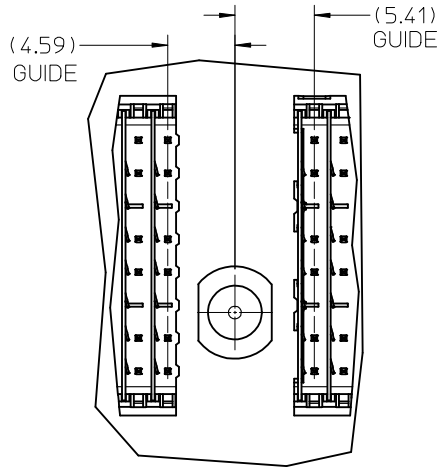
DRAWN BY: MWANG DATE: 2000/03/17
CHECKED BY: JLAURX DATE: 2000/03/20
APPROVED BY: CBIXLER DATE: 2000/03/20

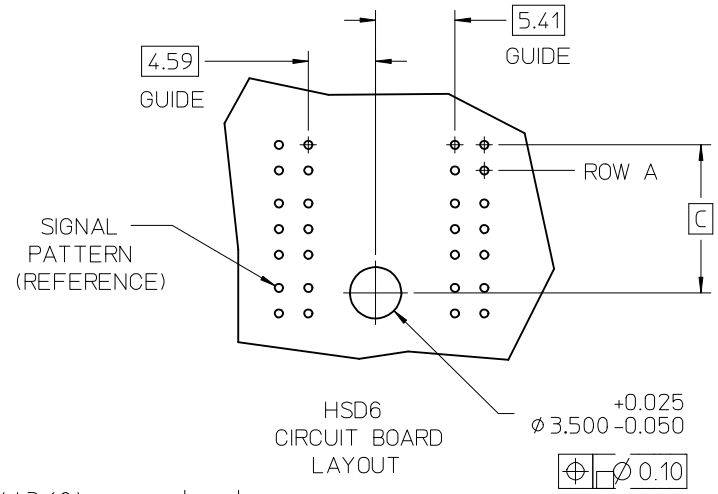
TITLE: VHDM BACKPALNE FREE STANDING GUIDE PIN OPEN ENDS SALES DRAWING

MOLEX INCORPORATED

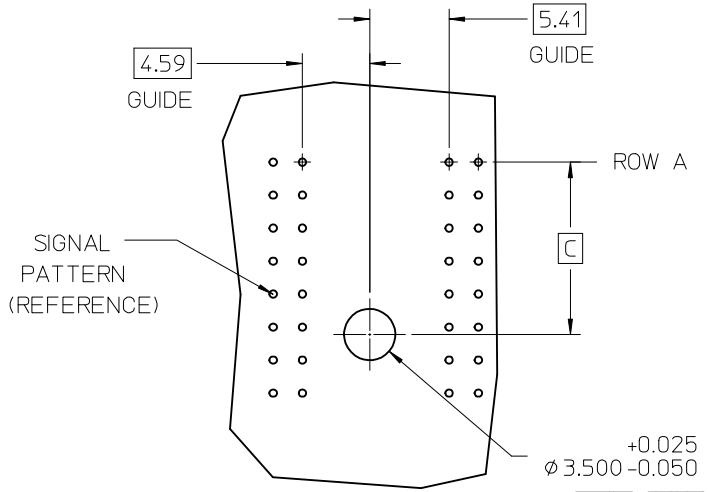
MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-74076-002
SHEET NO.: 1 OF 1
SIZE: B

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

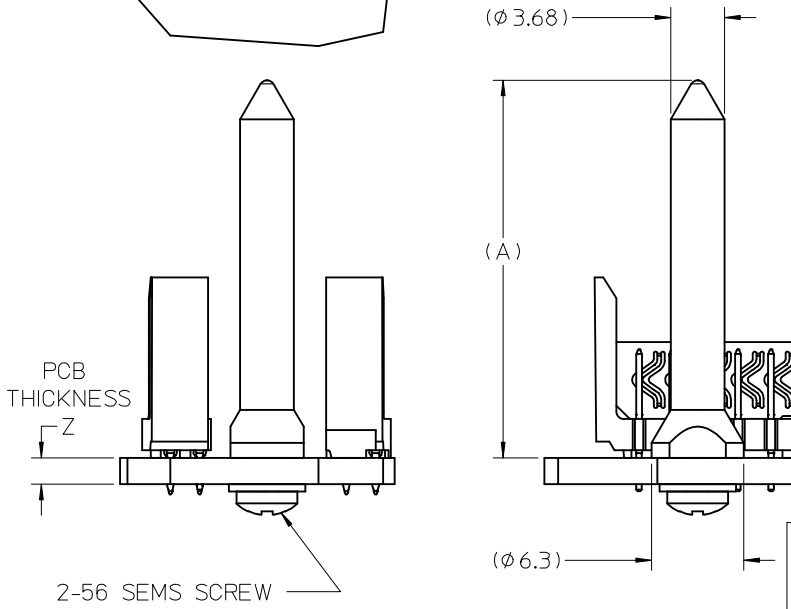




HSD6
CIRCUIT BOARD
LAYOUT



HSD8
CIRCUIT BOARD
LAYOUT



KIT NUMBER	DIM Z BOARD THICKNESS	DIM A
74076-0001	1.8 - 4.0	25.8
74076-0002	>4.0 - 9.0	25.8
74076-0005	1.8 - 4.0	19.9
74076-0006	>4.0 - 9.0	19.9

MATE WITH		DIM C
HSD 6	GUIDE MODULE	10.09
	GROUND MODULE	9.39
	JOINER MODUEL	9.39
HSD 8	GUIDE MODULE	11.75
	GROUND MODULE	11.75
	JOINER MODULE	11.75

NOTES:
1. PARTS TO BE BULK PACKED, 500 PER BAG.
2. SCREWS & GUIDE PINS PACKAGED SEPARATELY.

ADD PARTS
EC NO: UCP2009-0672 2008/09/18
DRWN: JBINGHAM 2008/09/19
CH'KD:
APPR: JLAURX 2008/09/19
DESCRIPTION
B
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.10	± ---
1 PLACE	± 0.15	± ---
ANGULAR ±---°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 3:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	JBINGHAM	2007/03/28
CHECKED BY	SREED	2007/03/28
APPROVED BY	SREED	2007/03/28

TITLE: HSD BACKPLANE FREE STANDING GUIDE PIN SALES DRAWING

MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-74076-005
SHEET NO.: 1 OF 1
SIZE: B

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

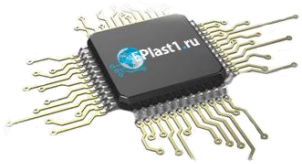
Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)
Факс: 8 (812) 320-02-42
Электронная почта: org@eplast1.ru
Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.